WURTH ELEKTRONIK MORE THAN YOU EXPECT



CHIP ON BOARD/WIRE BONDING

Design Rules for Aluminium (AI) wire bonding





Wire bonded diode in a multi-step Lasercavity

Design Rules for Gold (Au) wire bonding

CHIP PAD TO SUBSTRATE PAD MUST BE ALIGNED IN THE SAME DIRECTION.







REM magnification of a wire bonded diode in a multi-step Lasercavity





MORE SUPPORT THAN YOU EXPECT

wirebonding@we-online.com

Do you have questions about fabrication data, tolerances, test documentation or packaging? In our Technical Delivery Specification for printed circuit boards (TDS) you will find our standards and recommendations for smooth and effective cooperation.

www.we-online.com